

ABSTRACT

Provided are a film for manufacturing semiconductor component and a film for electronic component manufacture which can be easily removed from the table surface after stopping suction even when used in an environment accompanied by a change in temperature, and can stabilize the close contact state with the table surface. Furthermore, a method for manufacturing a semiconductor component using such a film for manufacturing semiconductor component, and a method for manufacturing an electronic component using such a film for electronic component manufacture are provided. The present film 1 for component manufacture is a film used for a method for manufacturing a semiconductor component or an electronic component, and comprises a base layer 11 and an adhesive layer 12 provided on one surface 11a side of the base layer 11, and the Ra (μm) of the surface of one side of the base layer on which the adhesive layer is not provided is 0.1 to 2.0, and the Rz (μm) is 1.0 to 15. The present method uses the film 1 for component manufacture, and includes a segmenting step, a pickup step, and an evaluation step prior to the pickup step.

[Fig. 1]